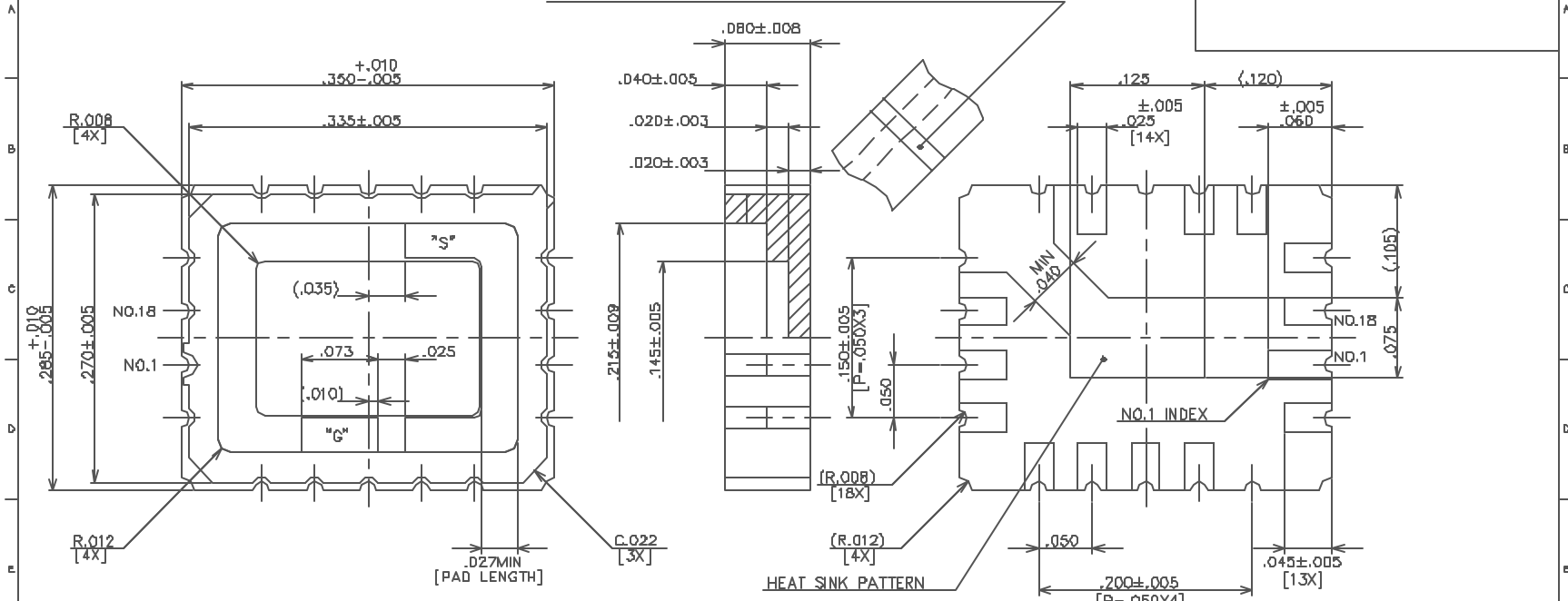


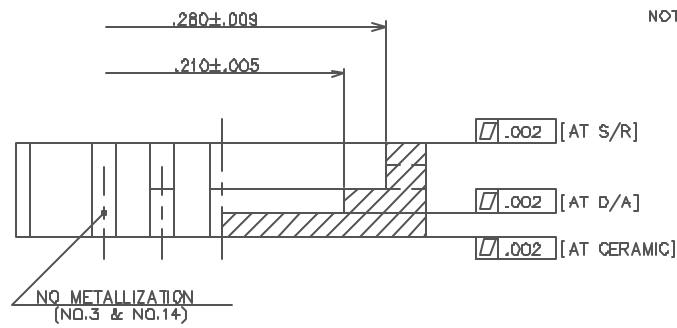


THIS METALLIZATION TO BE ELECTRICALLY CONNECTED TO THE HEAT SINK PATTERN AND SEAL RING

LATEST REVISION 9 DESCRIPTION	
B	CHG. CUSTOMER



- NOTES:
1. GOLD PLATE 25~50? INCHES OVER 80? INCHES MIN NICKEL.
 2. LEADS NO.1,2,15,16,17 AND 18 DON'T HAVE BOND FINGER. BOND PAD "G" IS CONNECTED TO NO.5 AND 4 LEADS. BOND PAD "S" IS CONNECTED TO NO.6,7,8,9,10,11,12 AND 13 LEADS.
 3. LEADS NO.1,2,15,16,17 AND 18 TO BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD.
 4. SEAL RING TO BE ELECTRICALLY CONNECTED TO LEADS NO.6,7,8,9,10,11,12 AND 13.
 5. BACK METALLIZATION OF LEADS NO.3 AND 14 WILL BE DELETED FOR ISOLATION.
 6. RESISTANCE : 20m? MAX (AT NEAREST POINT)

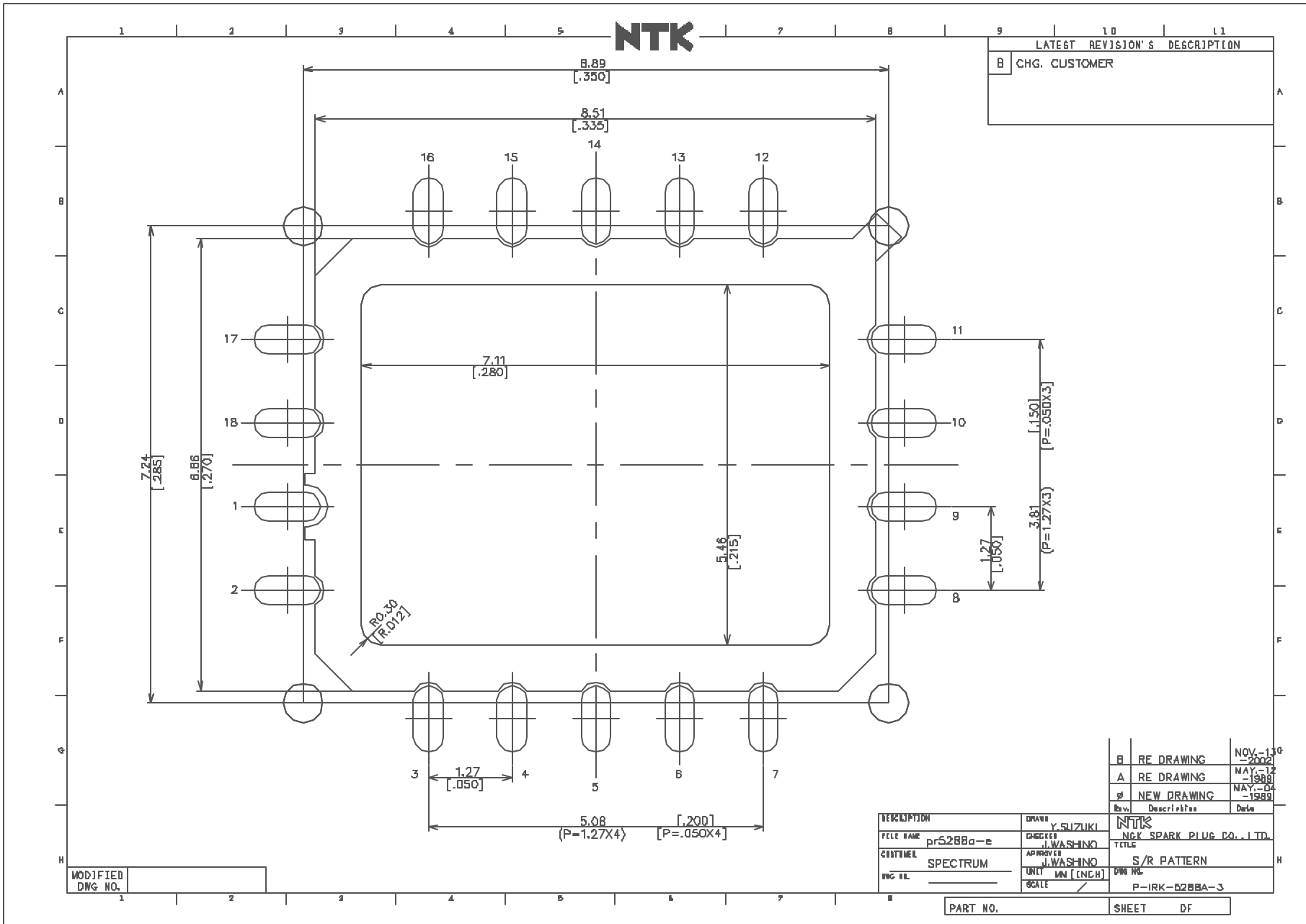


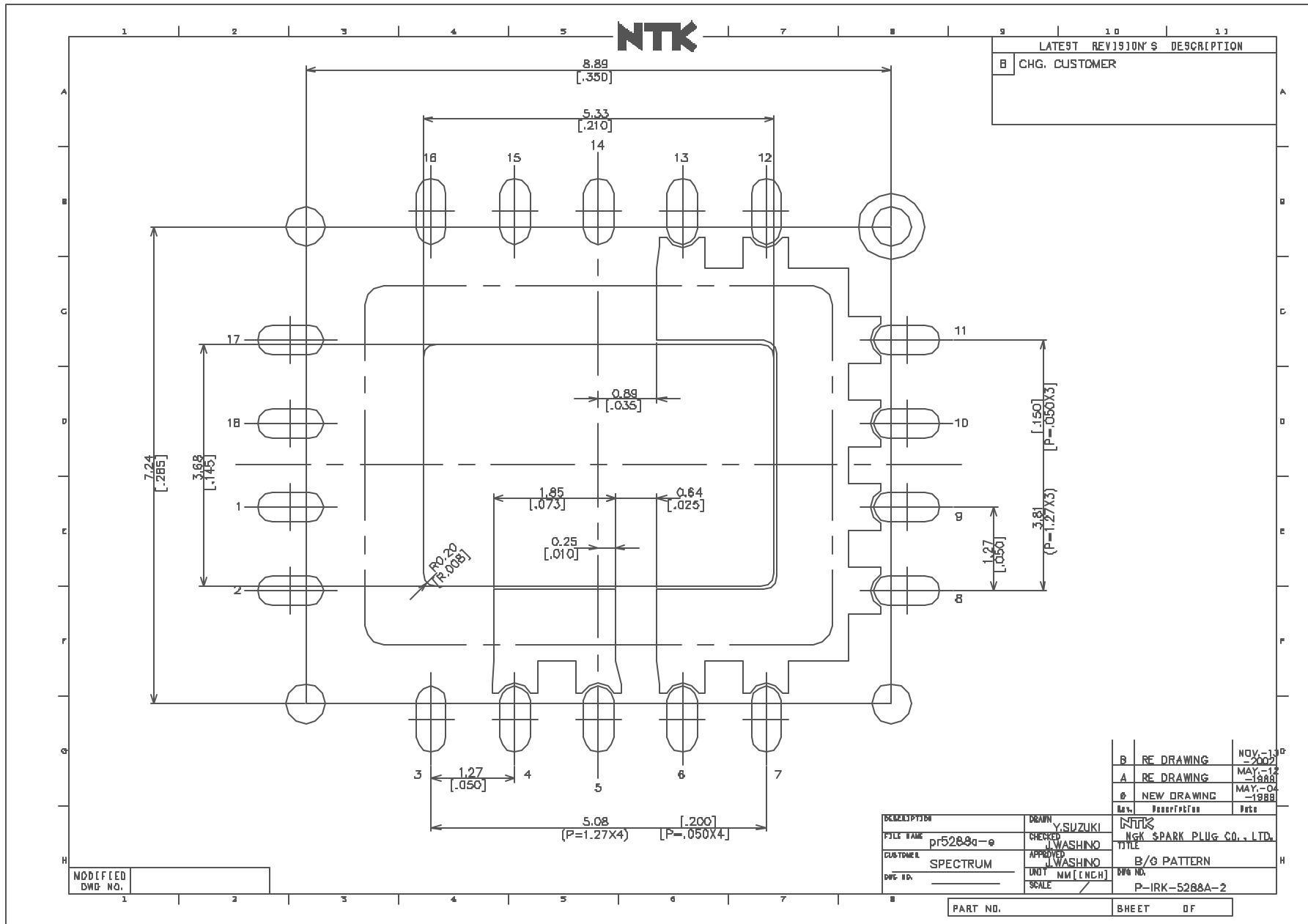
③			B	RE DRAWING	NOV-13-2002
②			A	RE DRAWING	MAY-12-1995
①	CERAMIC	BLACK ALUMINA	①	NEW DRAWING	MAY-04-1986
Drawn	N. L. T.	Material	Description	Rev.	Description
UNLESS OTHERWISE SPECIFIED TOLERANCES ± .001	DRW	Y. SUZUKI	NTK		
CHECKED	N. L. T.	J. WASHINO	Ngk SPARK PLUG CO., LTD.		
CUSTOMER	SPECTRUM	APPROVER	J. WASHINO	TITLE	18 LEAD CHIP CARRIER
DWG. NO.		UNIT	MM	DWG. NO.	IRK18F1-52BBA
		SCALE			

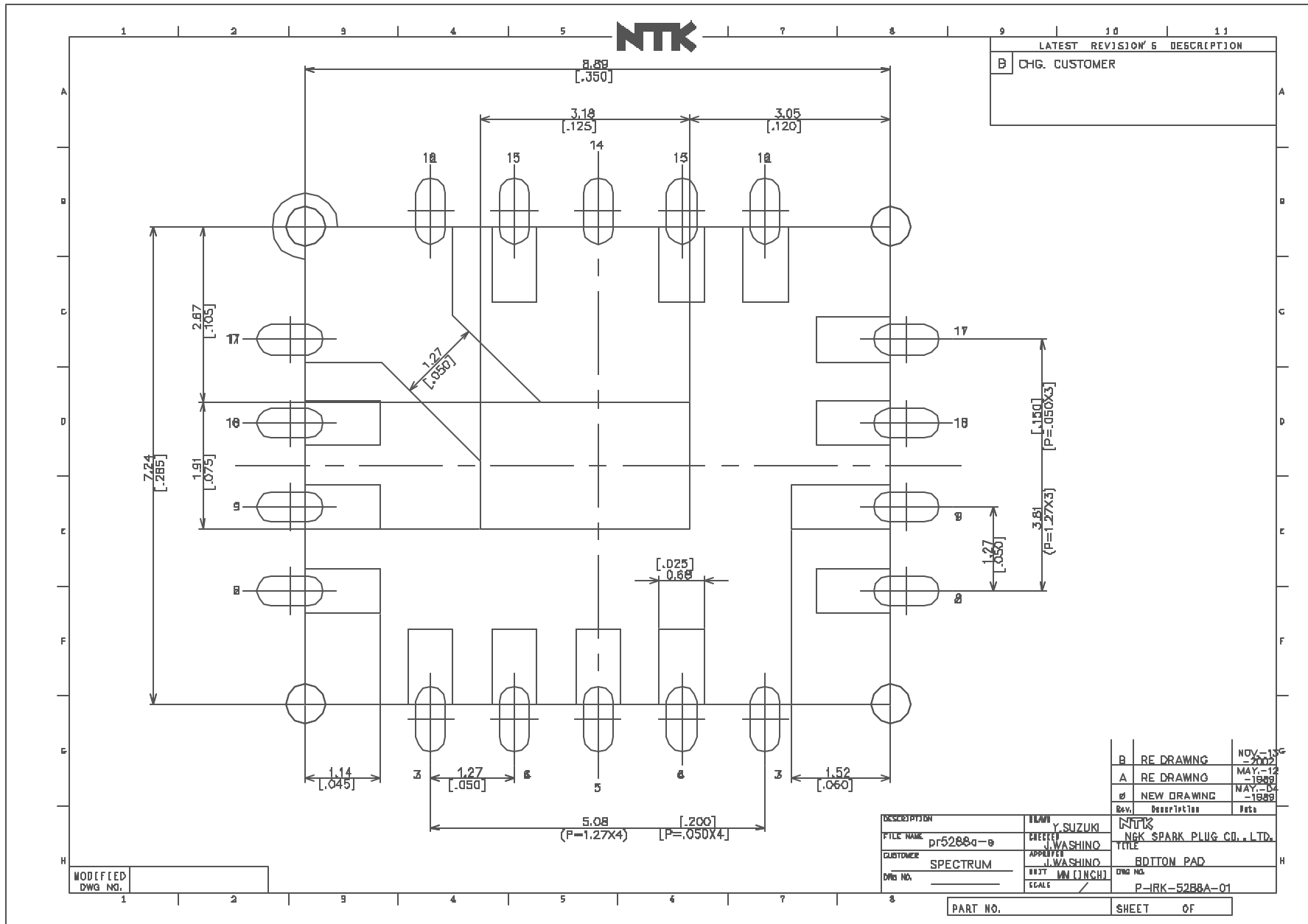
MODIFIED DWG NO. 1

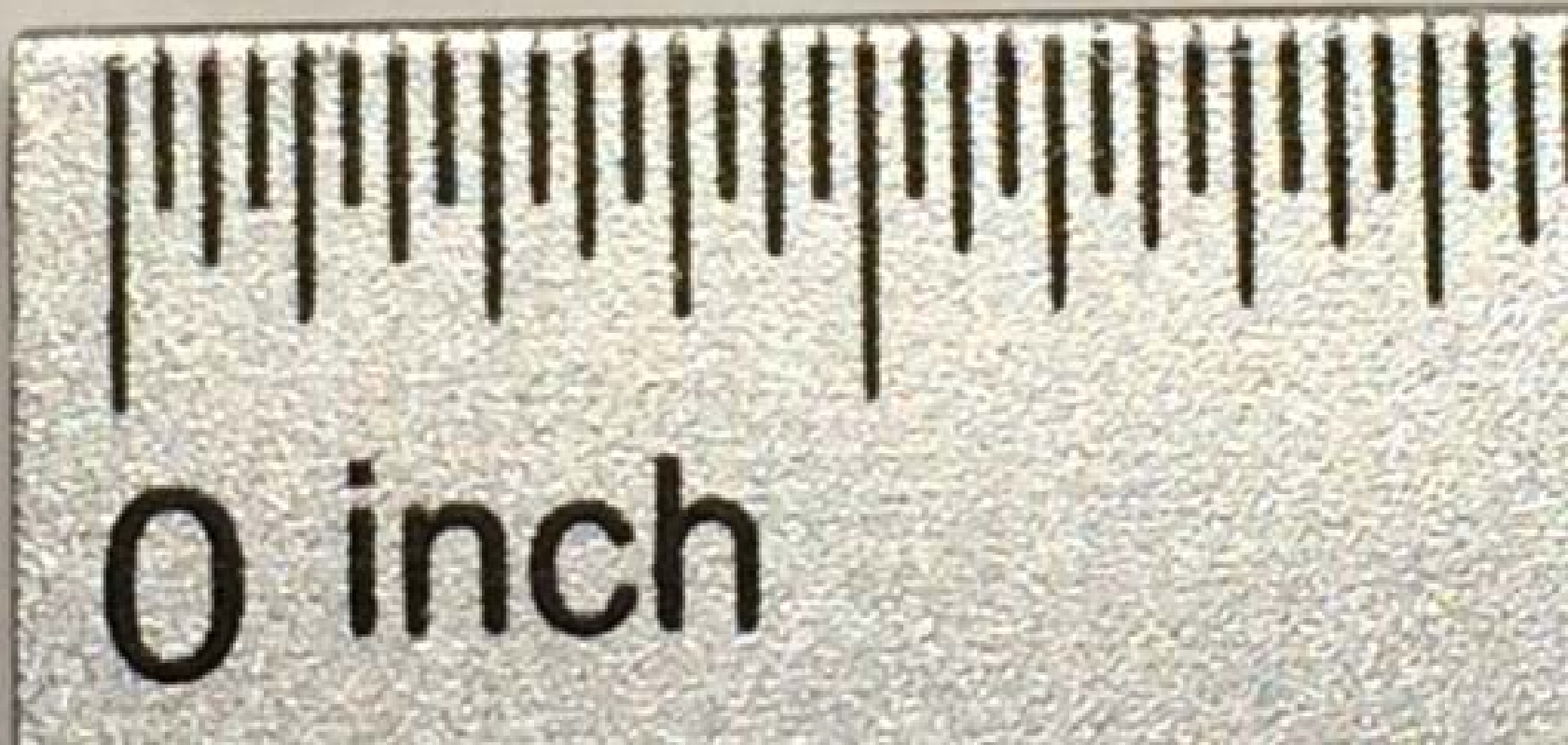
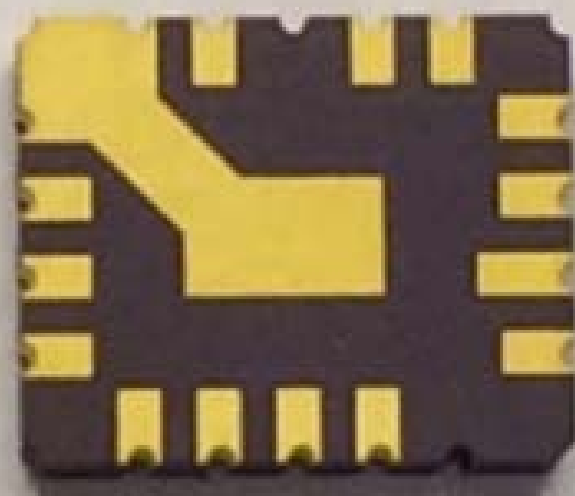
PART NO. SHEET 1 OF 1











0 inch